MCD56-14io1B

=

=

 V_{RRM}

I TAV

VT

 $= 2 \times 1400 \text{ V}$

60 A

1.24 V

Thyristor \ Diode Module

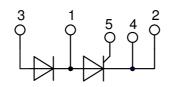
Phase	leg
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Part number

MCD56-14io1B



Backside: isolated **E**72873



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al2O3-ceramic

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: TO-240AA

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Terms Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office. Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office. Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

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Data according to IEC 60747and per semiconductor unless otherwise specified

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MCD56-14io1B

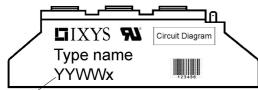
Symbol	Definition	Conditions		min.	ture	max	Uni
Symbol			$T_{vJ} = 25^{\circ}C$	min.	typ.	max. 1500	Uni
V _{RSM/DSM}	max. non-repetitive reverse/forwa		$T_{vJ} = 25 °C$ $T_{vJ} = 25 °C$			1400	,
V _{RRM/DRM}	max. repetitive reverse/forward b	* *					
R/D	reverse current, drain current	V _{R/D} = 1400 V	$T_{VJ} = 25^{\circ}C$			200	μ/
		V _{R/D} = 1400 V	$T_{VJ} = 125^{\circ}C$			5	m/
V _T	forward voltage drop	$I_{T} = 100 \text{ A}$	$T_{vJ} = 25^{\circ}C$			1.26	١
		$I_{T} = 200 \text{ A}$				1.57	١
		$I_{T} = 100 \text{ A}$	$T_{VJ} = 125 ^{\circ}C$			1.24	١
		$I_{T} = 200 \text{ A}$				1.62	١
I _{tav}	average forward current	$T_c = 85^{\circ}C$	$T_{vJ} = 125^{\circ}C$			60	ļ
I _{T(RMS)}	RMS forward current	180° sine				94	1
V _{T0}	threshold voltage	oss calculation only	$T_{vJ} = 125^{\circ}C$			0.85	١
r _T	slope resistance f Tor power i					3.7	m۵
R _{thJC}	thermal resistance junction to cas	se				0.45	K/W
R _{thCH}	thermal resistance case to heats	ink			0.20		K/W
Ptot	total power dissipation		$T_c = 25^{\circ}C$			222	W
I _{TSM}	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{v,l} = 45^{\circ}C$			1.50	k/
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			1.62	k/
		t = 10 ms; (50 Hz), sine	T _{v.i} = 125°C			1.28	k/
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			1.38	k/
l²t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{\rm VJ} = 45^{\circ}\rm C$			11.3	
		t = 8,3 ms; (60 Hz), sine	$V_{\rm R} = 0 V$			10.9	1
		t = 0,0 ms; (50 Hz), sine t = 10 ms; (50 Hz), sine	$T_{\rm V,I} = 125^{\circ}{\rm C}$			8.13	kA ²
		t = 8,3 ms; (60 Hz), sine	$V_{\rm R} = 0 V$			7.87	
C	junction capacitance	$V_{\rm B} = 400 \text{V}$ f = 1 MHz	$\frac{V_{R} = 0.7}{T_{VJ} = 25^{\circ}C}$		74	7.07	pF
-		$t_{\rm P} = 30 \mu {\rm s}$	$T_{v_{J}} = 25 \text{ C}$ $T_{c} = 125 \text{ C}$		/4	10	ېر ۷
P _{GM}	max. gate power dissipation	$t_{\rm P} = 300 \mu {\rm s}$ $t_{\rm P} = 300 \mu {\rm s}$	$1_{\rm C} = 125 \rm C$			5	N
D		$l_{\rm P} = 300\mu{\rm s}$				-	1
P _{GAV}	average gate power dissipation	T (0500 (50 H				0.5	N A (
(di/dt) _{cr}	critical rate of rise of current		epetitive, $I_T = 150 \text{ A}$			150	A/μ
		$t_{\rm P}$ = 200 µs; di _G /dt = 0.45 A/µs; -					
			on-repet., $I_{T} = 60 \text{ A}$			500	
(dv/dt) _{cr}	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^{\circ}C$			1000	V/µs
		$R_{GK} = \infty$; method 1 (linear volta					
V _{ат}	gate trigger voltage	$V_{D} = 6 V$	$T_{vJ} = 25^{\circ}C$			1.5	١
			$T_{vJ} = -40 ^{\circ}C$			1.6	١
I _{GT}	gate trigger current	$V_{D} = 6 V$	$T_{vJ} = 25^{\circ}C$			100	mÆ
			$T_{vJ} = -40^{\circ}C$			200	m/
V _{gd}	gate non-trigger voltage	$V_{\rm D} = \frac{2}{3} V_{\rm DRM}$	$T_{v_{J}} = 125^{\circ}C$			0.2	١
I _{gd}	gate non-trigger current					10	mA
۱	latching current	t _p = 10 μs	$T_{vJ} = 25 °C$			450	m/
		$I_{\rm G} = 0.45 \text{A}; \text{di}_{\rm G}/\text{dt} = 0.45 \text{A}/\mu\text{s}$					
I _H	holding current	$V_{\rm D} = 6 V R_{\rm GK} = \infty$	$T_{vJ} = 25 ^{\circ}C$			200	m/
t _{gd}	gate controlled delay time	$V_{\rm D} = \frac{1}{2} V_{\rm DRM}$	$T_{vJ} = 25^{\circ}C$			2	μ
-ya	<u> </u>	$I_{\rm G} = 0.45 \text{A}; \text{di}_{\rm G}/\text{dt} = 0.45 \text{A}/\mu\text{s}$				-	P ⁴⁴
t _q	turn-off time	$V_{\rm R} = 100 \text{ V}; \ \text{I}_{\rm T} = 150 \text{ A}; \ \text{V} = 3200 \text{ V}; \ \text{V}_{\rm R} = 100 \text{ V}; \ \text{V}_{\rm T} = 100 \text{ V}; \ \text{V}; \ \text{V}_{\rm T} = 100 \text{ V}; \ \text{V}; \ \text{V}_{\rm $			150		
La	carri on unio	$v_{\rm R} = 100 v$, $I_{\rm T} = 100 A$, $v = 7$	S VDRM IVJ = IUU U		150		μ

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MCD56-14io1B

Package	TO-240AA				F	Rating	S	
Symbol	Definition	Conditions			min.	typ.	max.	Unit
	RMS current	per terminal					200	Α
T _{vj}	virtual junction temperature				-40		125	°C
T _{op}	operation temperature				-40		100	°C
T _{stg}	storage temperature				-40		125	°C
Weight						81		g
M _D	mounting torque				2.5		4	Nm
M _T	terminal torque				2.5		4	Nm
d _{Spp/App}	creenade distance on surfac	e l striking distance through air	terminal to terminal	13.0	9.7			mm
d _{Spb/Apb}	creepage distance on surface striking distance through air		terminal to backside	16.0	16.0			mm
V	isolation voltage	t = 1 second			3600			V
		t = 1 minute	50/60 Hz, RMS; liso∟ ≤ 1 mA		3000			V



Date Code

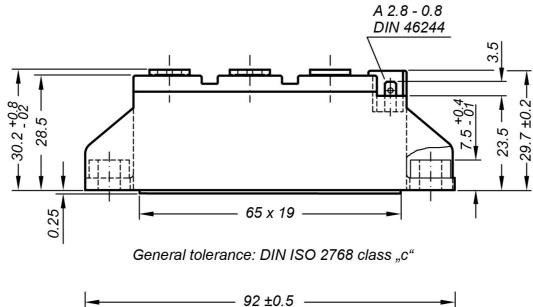
[Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
	Standard	MCD56-14io1B	MCD56-14io1B	Box	36	464848

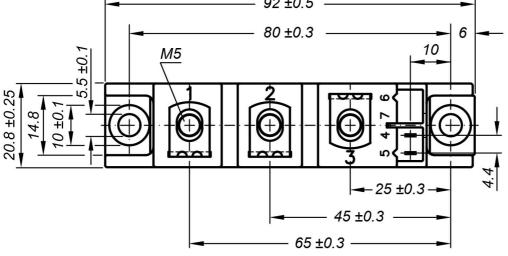
Similar Part	Package	Voltage class
MCMA65PD1600TB	TO-240AA-1B	1600
MCMA85PD1600TB	TO-240AA-1B	1600

Equiva	lent Circuits for	Simulation	* on die level	T _{vj} = 125 °C
	⊢R₀−	Thyristor		
V _{0 max}	threshold voltage	0.85		V
$\mathbf{R}_{0 \max}$	slope resistance *	2.5		mΩ

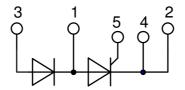
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Outlines TO-240AA





Optional accessories: Keyed gate/cathode twin plugs Wire length: 350 mm, gate = white, cathode = red UL 758, style 3751 Type **ZY 200L** (L = Left for pin pair 4/5)



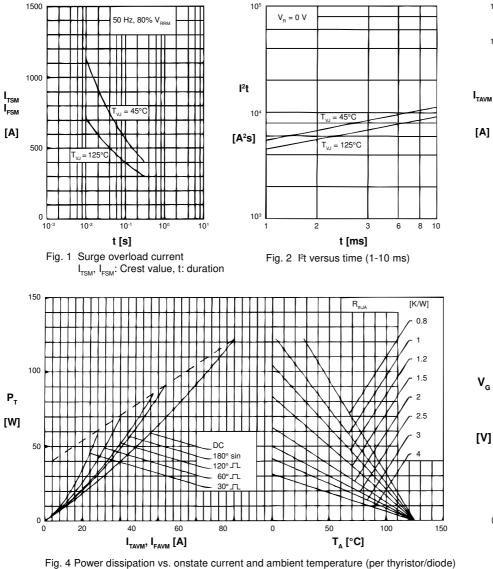
DC

180° sin 120°-√_

60° _⊤_ 30° □

150

Thyristor



600 R_{thK} [K/W] 0.1 500 0.15 0.2 400 0.25 \mathbf{P}_{tot} 0.3 300 [W] 0.4 0.5 200 0.6 Circuit B6 3x MCC56 or 100 3x MCD56 0 50 100 150 0 50 100 150 I_{dAVM} [A] T_^ [°C] Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current

120

100

80

60

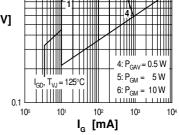


Fig. 5 Gate trigger charact.

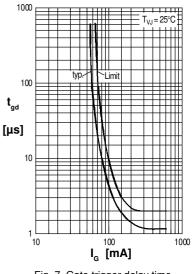


Fig. 7 Gate trigger delay time

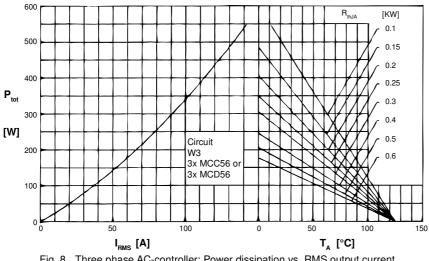
and ambient temperature

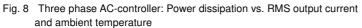
[[]A] 40 20 0 50 100 0 **T**_c [°**C**] Fig. 3 Maximum forward current at case temperature 10 1: I_{GT} , $T_{VJ} = 125^{\circ}C$ 2: I_{GT} , T_{VJ} = 25°C 3: I_{GT} , T_{VJ} = -40°C ۷_g [V]

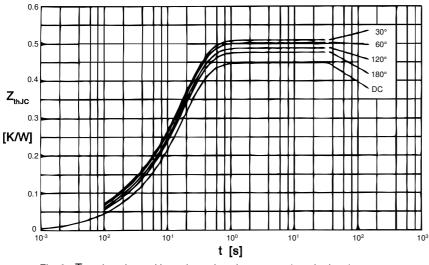
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Rectifier



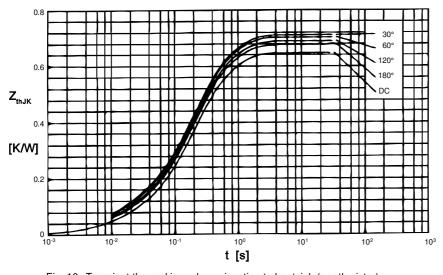




R _{thJC} for varie	ous conduction angles d:
d R _t	_{ujc} [K/W]
DC	0.450
180°	0.470
120°	0.490
60°	0.505
30°	0.520
Constants fo	$r Z_{thJC}$ calculation:
i R _{thi} [K/W] t _i [s]
1 0.014	0.0150

1	0.014	0.0150
2	0.026	0.0095
3	0.410	0.1750

Fig. 9 Transient thermal impedance junction to case (per thyristor)



$R_{_{thJK}}$	for vario	ous conduction angles d:
	d R _u	_{лж} [К/W]
	DC	0.650
	180°	0.670
	120°	0.690
	60°	0.705
	30°	0.720
Con	stants fo	$r Z_{thJK}$ calculation:
i F	R _{thi} [K/W] t _i [s]
1	0.014	0.0150
2	0.026	0.0095
3	0.410	0.1750
4	0.200	0.6700

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Fig. 10 Transient thermal impedance junction to heatsink (per thyristor)

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